Material Data Declaration Sheet - v003

Version 2.0

Supplier Information

Company Name *	Intel Corporation
Response Document ID	104784
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Contact Name *	Ooi, Khye Lin
Contact Title *	Intel Product Ecology
Contact Phone *	1-800-628-8686
Contact Email *	productecology@intel.com

Supplier Comments

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Product(s)

Product Family Name:

Requester Item Number	Item Number *	Description	Effective Date *	Mass *	UoM*	Comment
	A5EC065BB32XXXX	Agilex™ 5 FPGA E-Series 065B (B32A) A5EC065BB32XXXX	2025-12-10	3.601	g	

Product Part(s)

ID*	Description	Effective Date*	Units*	% of Product Mass	Comment	
Capacitor 2	Capacitor	2025-12-10	2	0.067		
Capacitor 4	Capacitor	2025-12-10	12	0.067		
Die	Die	2025-12-10	1	7.581		
Solder Spheres	Solder Spheres	2025-12-10	1	11.001		
SOLDER-PASTE 1	SOLDER-PASTE	2025-12-10	1	0.389		
SOLDER-PASTE 3	SOLDER-PASTE	2025-12-10	1	0.278		
Substrate	Substrate	2025-12-10	1	80.063		
Underfill	Underfill	2025-12-10	1	0.555		

Declaration

LHPLA	This product is Low Halogen (Components): Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. The replacement of halogenated flame retardants may not be better for the environment. Intel Components as well as purchased components on the finished assembly meet the joint JEDEC/ECA JS-709B requirement.	True
LHPWB	This product is Low Halogen (PCB): Applies Br/Cl in the PCB Laminate. The PCB / Substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants may not be better for the environment	True
REACH-1125	Product(s) is obsolete, no information is available	False
REACH-1125	Product(s) is unknown, no information is available	False
REACH-1125	Product(s) does not contain EU REACH Candidate List substances above the thresholds specified in the REACH Regulation	True
EUROHS-1506	Product(s) does not meet EU RoHS requirements and is not under exemptions	False
EUROHS-1506	Product(s) is obsolete, No Information is Available	False
EUROHS-1506	Product(s) is unknown, no information is available	False
EUROHS-1506	Product(s) Meets EU RoHS Requirements by Application of the Selected Exemption(s)	False
EUROHS-1506	Product(s) Meets EU RoHS Requirements Without Any Exemptions	True

Signature

Intel Product Ecology	C=US, E=productecology@intel.com, OU="", O=Intel Corporation, CN=Intel Product Ecology

Part ID	Description		# of Units	Part Mass %
Capacitor 2	Capacitor		2	0.067

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
Ceramic element/Ceramics		mg	0.688		1304-28-5	Barium Oxide	ppm	600000.000	
						Misc	ppm	100000.000	
					13463-67-7	Titanium dioxide	ppm	300000.000	
Inner electrode/Nickel and Nickel alloys		mg	0.373	00031	7440-02-0	Nickel	ppm	1000000.000	
Nickel Plating Layer/Nickel plating		mg	0.011	00031	7440-02-0	Nickel	ppm	1000000.000	
Outer electrode/Copper alloys 1		mg	0.092		7440-50-8	Copper	ppm	1000000.000	
Outer electrode/Copper alloys 2		mg	0.010	00075	-	Proprietary	ppm	203883.495	
					7631-86-9	Silicon Dioxide	ppm	796116.505	
Tin Plating Layer/Tin plating		mg	0.025		7440-31-5	Tin	ppm	1000000.000	

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Part ID	Description		# of Units	Part Mass %
Capacitor 4	Capacitor		12	0.067

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
Ceramic		mg	0.139		1304-28-5	Barium Oxide	ppm	600000.000	
						Misc	ppm	100000.000	
					13463-67-7	Titanium dioxide	ppm	300000.000	
Copper alloys		mg	0.029		7440-50-8	Copper	ppm	1000000.000	
Glass		mg	0.003	00075	-	Proprietary	ppm	187500.000	
					7631-86-9	Silicon Dioxide	ppm	812500.000	
Nickel and Nickel alloys		mg	0.009	00031	7440-02-0	Nickel	ppm	1000000.000	
Nickel plating		mg	0.009	00031	7440-02-0	Nickel	ppm	1000000.000	
Tin plating		mg	0.011		7440-31-5	Tin	ppm	1000000.000	

Part ID	Description		# of Units	Part Mass %
Die	Die		1	7.581

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
Die Silicon Material (Generic)		massPercent	99.200			Proprietary Doped Silicon	ppm	1000000.000	
Passivation Layer (143907-02-2)		massPercent	0.800	00193	143907-02-2	Poly(oxy-1,2-ethanediyl), α,α',α'',α'''-(oxydi-3,1,2-	ppm	1700.000	
						Proprietary ingredients	ppm	998300.000	

Part ID	Description		# of Units	Part Mass %
Solder Spheres	Solder Spheres		1	11.001

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
ECO SOLDER BALL S #7097 0.4mm		mg	396.159		7440-50-8	Copper	ppm	5000.000	
					7440-22-4	Silver	ppm	40000.000	
					7440-31-5	Tin	ppm	955000.000	

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Part ID	Description		# of Units	Part Mass %
SOLDER-PASTE 1	SOLDER-PASTE		1	0.389

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
ECO SOLDER PASTE M705-PiN40 Type6		mg	14.000		670-96-2	1H-Imidazole, 2-phenyl-	ppm	80000.000	
					112-59-4	2-((2-Hexyloxy)ethoxy) Ethanol	ppm	140000.000	
					110-99-6	Acid	ppm	30000.000	
					7440-50-8	Copper	ppm	3000.000	
					123-26-2	Octadecanamide, N,N'-1,2-ethanediylbis[12-hydroxy-	ppm	20000.000	
					65997-05-9	Rosin	ppm	130000.000	
					7440-22-4	Silver	ppm	18000.000	
					7440-31-5	Tin	ppm	579000.000	

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Part ID	Description		# of Units	Part Mass %
SOLDER-PASTE 3	SOLDER-PASTE		1	0.278

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
Alpha-Terpineol		mg	0.110		98-55-5	3-Cyclohexene-1-methanol, .alpha.,.alpha.,4-trimethyl-	ppm	1000000.000	
Copper		mg	0.045		7440-50-8	Copper	ppm	1000000.000	
Organic acid		mg	0.088		110-99-6	Acid	ppm	1000000.000	
Organic amine		mg	0.191		65605-36-9	Poly oxy ethylene diam	ppm	1000000.000	
Organic amine 2		mg	0.105		25214-63-5	1,2-Ethanediamine, polymer with 2-methyloxirane	ppm	1000000.000	
Polymer		mg	0.132		25322-68-3	Polyethylene glycol	ppm	1000000.000	
Silver		mg	0.089		7440-22-4	silver	ppm	1000000.000	
Solvent		mg	0.143		1559-36-0	Diethylene glycol-2-ether	ppm	1000000.000	
Solvent 2		mg	0.099		122-99-6	2-phenoxyethanol	ppm	1000000.000	
Surfactant		mg	0.160		26635-93-8	Polyoxyrthylene Alkylamine	ppm	1000000.000	
Surfactant 2		mg	0.072		1338-39-2	Sorbitan, monododecanoate	ppm	1000000.000	
Tin		mg	8.766		7440-31-5	Tin	ppm	1000000.000	

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Part ID	Description		# of Units	Part Mass %
Substrate	Substrate		1	80.063

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
Printed Circuit Board		g	2.883		7727-43-7	Barium Sulfate	ppm	2391.359	
					7440-50-8	Copper	ppm	573083.070	
						Epoxy Resin	ppm	115118.271	
					65997-17-3	Fibrous-Glass-Wool	ppm	153425.626	
					7440-57-5	Gold	ppm	1.175	
				00031	7440-02-0	Nickel	ppm	5418.164	
					7440-05-3	Palladium	ppm	0.654	
					7631-86-9	Silicon Dioxide	ppm	145058.247	
					64742-94-5	Solvent Naphtha (Petroleum), Heavy Aroma	ppm	5503.434	

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Part ID	Description		# of Units	Part Mass %
Underfill	Underfill		1	0.555

Homogenous Material Name	Material Class ID	HM Mass UoM	HM Mass Value	Substance Group	Substance Identity	Substance	Substance Mass UoM	Substance Mass Value	Exemption
XS8410-428ND		mg	20.000		25068-38-6	(CHLOROMETHYL)OXIRANE, 4,4'-(1-	ppm	6100.000	
					27610-48-6	6-glycidyloxynapht-1-yl oxymethyloxirane	ppm	35000.000	
						Additives	ppm	8700.000	
						Amine type hardener	ppm	85000.000	
					9003-36-5	FORMALDEHYDE, POLYMER WITH (CHLOROMETHYL)OXIRANE	ppm	190000.000	
					603-35-0	Phosphine, triphenyl-	ppm	1900.000	
					60676-86-0	Silica, Vitreous	ppm	673300.000	

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